



128MB to 16GB  
CompactFlash Card



www.stec-inc.com

## SLCFxxx(M/G)M1(T2)U(I)

Solid-State Memory Card  
(No Moving Parts)

Capacity: 128MB - 16GB

CFA 3.0 and ATA-5 Compatible

ATA Transfer modes:

- PIO 0-6, MWDMA 0-4
- PIO 0-6 only (for applications that require MWDMA access to be disabled)

Supports TrueIDE and PC Card  
Memory and I/O Modes

Form Factors:

- CompactFlash Type I
- CompactFlash Type II
- CompactFlash Adapter

Endurance Guarantee of 2,000,000  
Write/Erase Cycles

Card Information Structure (CIS)  
Programmed into 256 Bytes of  
Internal Memory

PC Card and Socket Services  
Release 2.1 or later compatible

5V or 3.3V Power Supply

Commercial and Industrial  
Operating Temperature Range

5-Byte Detection, 4-Byte Correction  
ECC Engine

10 Year Data Retention

RoHS-6 Compliant

### General Description and Key Features

STEC's flash storage adheres to the latest industry compliance and regulatory standards including UL, FCC, RoHS, and various compliance associations. Each device incorporates a proprietary state-of-the-art flash memory controller that provides the greatest flexibility to customer-specific applications while supporting key flash management features resulting in the industry's highest reliability and endurance. Key features include:

- Built-in ECC engine detects up to 5-byte and corrects up to 4-byte errors
- Sophisticated block management and wear leveling algorithms guarantees 2,000,000 write/erase cycles
- Power-down data protection ensures data integrity and errors in case of power loss
- Lifecycle management feature allows users to monitor the device's block management

STEC's CF Card is the product of choice in applications requiring high reliability and high tolerance to shock, vibration, humidity, altitude, ESD, and temperature. The rugged industrial design combined with industrial temperature (-40°C to 85°C) testing and adherence to rigid JEDEC JESD22 standards ensures flawless execution in the harshest environments.

In addition to custom hardware and firmware designs, STEC also offers value-added services including:

- Custom labeling and packaging
- Custom software imaging and ID strings
- Full BOM control and product change notification
- Total supply-chain management to ensure continuity of supply
- In-field application engineering to help customers through product design-ins

### Ordering Information: CompactFlash Card

Part Number	CF Form Factor	Capacity
SLCF128MM1U(I)	Type I	128 Mbytes
SLCF256MM1U(I)	Type I	256 Mbytes
SLCF512MM1U(I)	Type I	512 Mbytes
SLCF1GM1U(I)	Type I	1 GByte
SLCF2GM1U(I)	Type I	2 GBytes
SLCF4GM1U(I)	Type I	4 GBytes
SLCF8GM1U(I)	Type I	8 GBytes
SLCF16GM1T2U(I)	Type II	16 GBytes

#### Legend:

- **SLCF** = STEC standard CF Card part number prefix.
- **(M/G)** = proceeding capacity (xxx) is in Megabytes (M) or Gigabytes (G).
- **M1** = STEC Mach 1 controller.
- **U** = RoHS-6 compliant lead-free.
- **Part numbers without (I)** = Commercial temperature range (0°C to 70°C).
- **(I)** = Industrial temperature range (-40°C to +85 °C).
- **F** = media set to fixed storage for non-removable IDE applications. Use with operating systems, such as Windows XP, that require storage media to be identified as a fixed drive before it can be used as a bootable drive. Example: SLCFxxx(M/G)M1(T2)U(I)-F.
- **P** = firmware programmed for PIO Modes 0-6 only for applications requiring MWDMA access to be disabled. Example: SLCFxxx(M/G)M1(T2)U(I)-P.
- **S** = optimized for applications that store small (1-4 sector) data packets, e.g. transactional data acquisition. Example: SLCFxxx(M/G)M1(T2)U(I)-S.

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## 1.0 Product Specifications

### 1.1 Labeling

STEC CF Cards can be manufactured with standard labeling, or customer-specific, custom labeling. Standard labeling is shown in Figure 1.

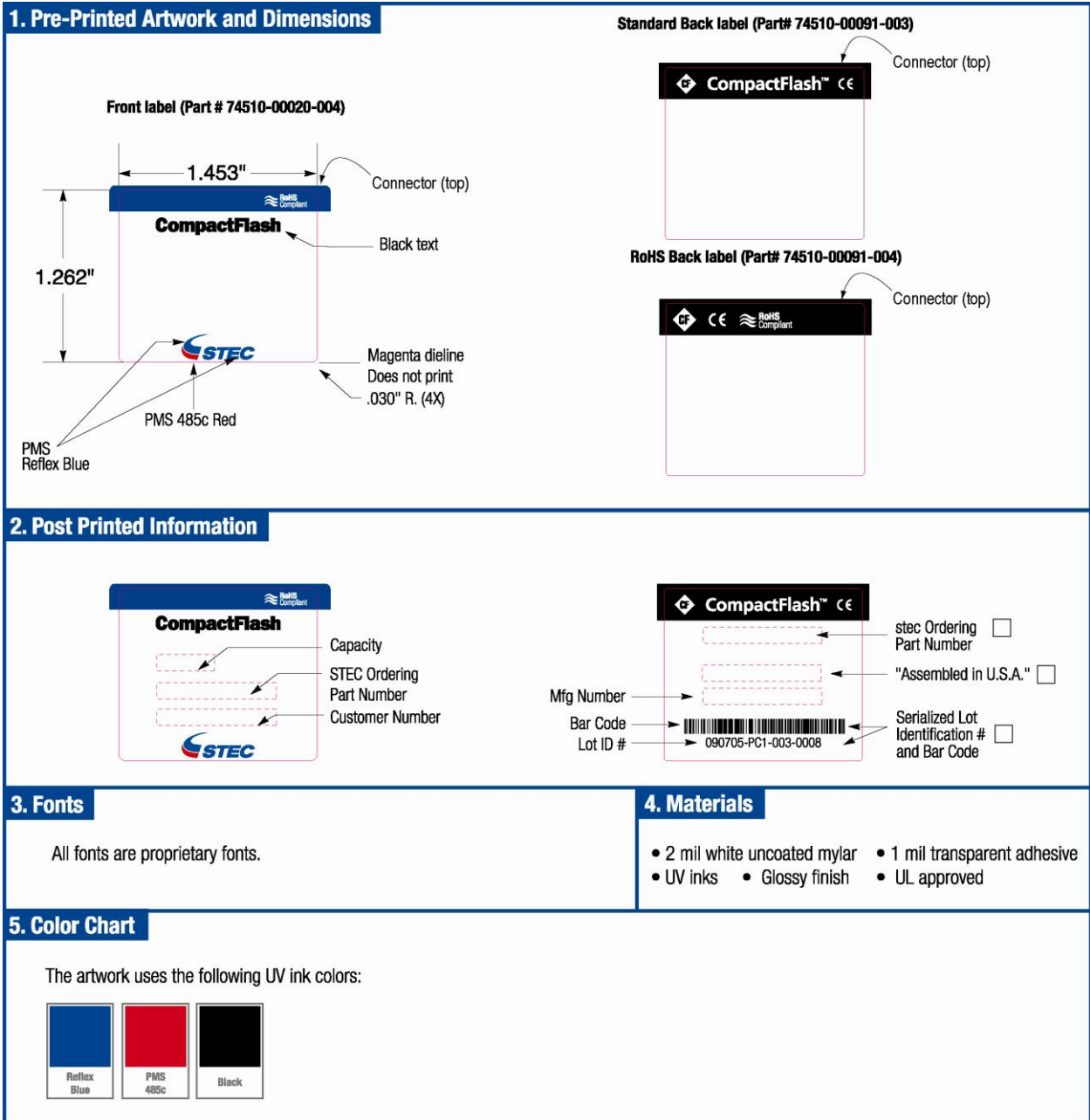


Figure 1: Standard Labeling

1.2 Package Dimensions and Pin Locations

1.2.1 CompactFlash Type I

Table 1 and Figure 2 show the mechanical dimensions of the CompactFlash Type I.

Table 1: Mechanical dimensions CompactFlash Type I

Parameter	Value
Length	36.40 ± 0.15 mm (1.433 ± 0.006 in)
Width	42.80 ± 0.10 mm (1.685 ± 0.004 in)
Height (including label area)	3.30 mm ± 0.10 mm (0.130 ± 0.004 in)

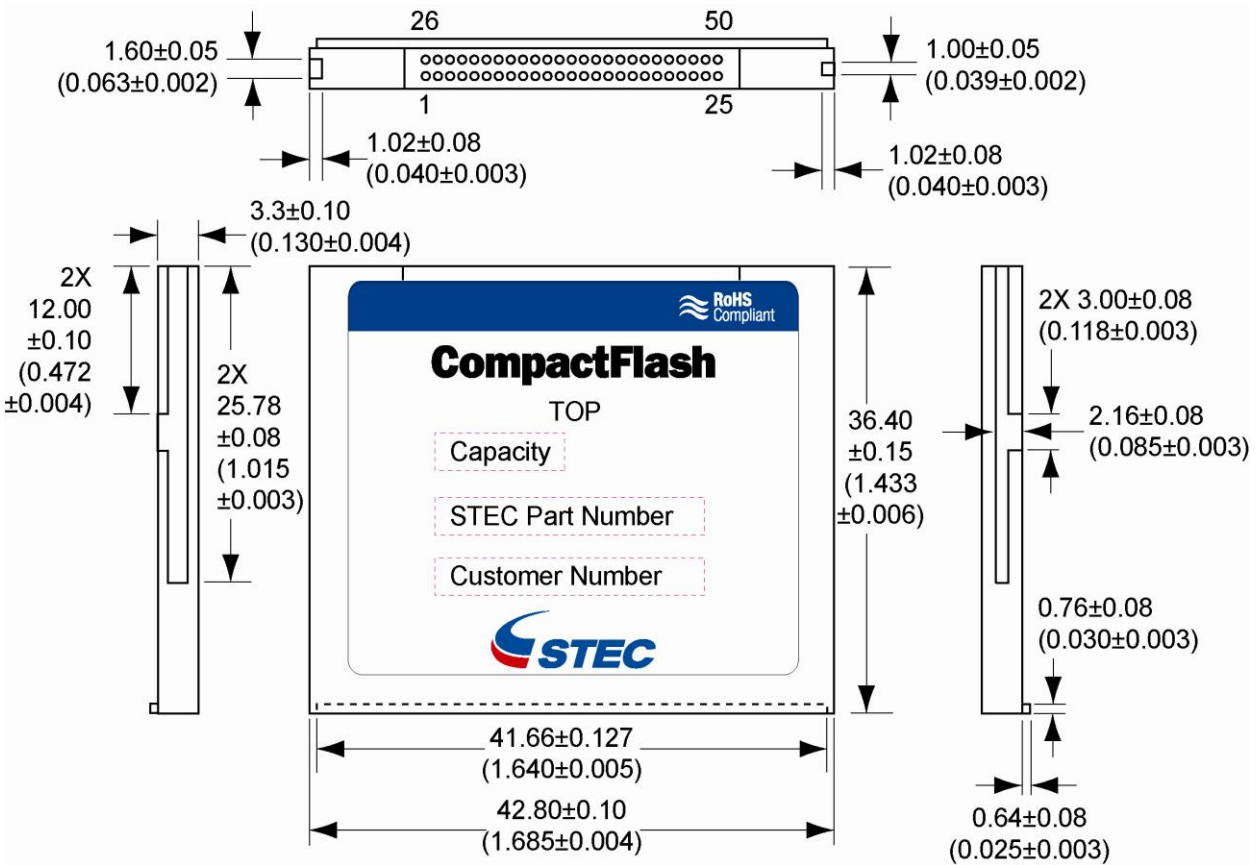


Figure 2: Mechanical dimensions CompactFlash Type I

1.2.2 CompactFlash Type II

Table 2 and Figure 3 show the mechanical dimensions of the CompactFlash Type II.

Table 2: Mechanical dimensions CompactFlash Type II

Parameter	Value
Length	36.40 ± 0.15 mm (1.433 ± 0.006 in)
Width	42.80 ± 0.10 mm (1.685 ± 0.004 in)
Height (including label area)	5.00 mm (0.197 in) max

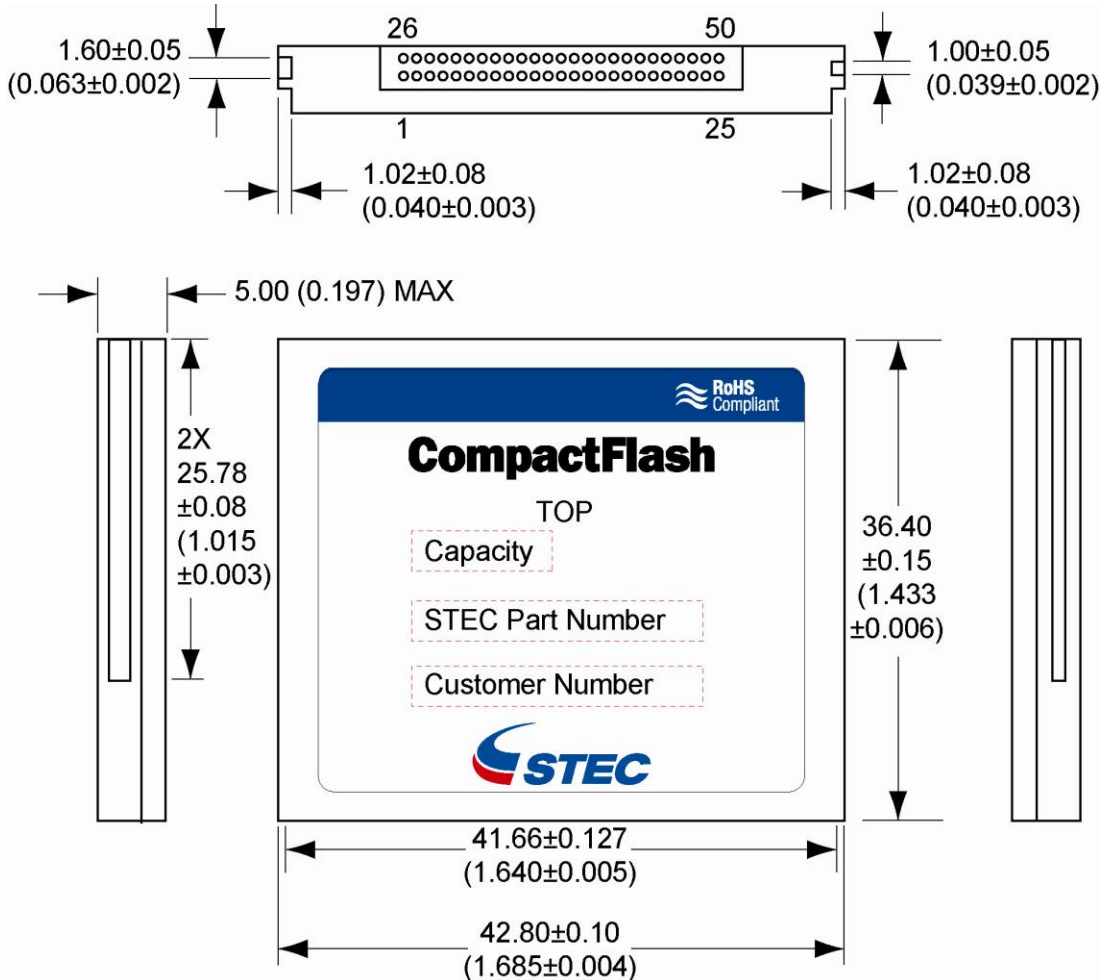


Figure 3: Mechanical dimensions CompactFlash Type II

### 1.3 Pin Assignment

Table 3: CF Card Pin Assignment

Pin Number	Signal Name	Pin Type	Pin Number	Signal Name	Pin Type
1	GND	Ground	26	-CD1	O
2	D03	I/O	27	D11	I/O
3	D04	I/O	28	D12	I/O
4	D05	I/O	29	D13	I/O
5	D06	I/O	30	D14	I/O
6	D07	I/O	31	D15	I/O
7	-CE1 -CS0	I	32	-CE2 -CS1	I
8	A10	I	33	-VS1	O
9	-OE -ATASEL	I	34	-IORD	I
10	A09	I	35	-IOWR	I
11	A08	I	36	-WE	I
12	A07	I	37	RDY/BSY -IREQ INTRQ	O
13	VCC	Power	38	VCC	Power
14	A06	I	39	-CSEL	I
15	A05	I	40	-VS2	O
16	A04	I	41	RESET -RESET	I
17	A03	I	42	-WAIT IORDY	O
18	A02	I	43	-INPACK DMARQ (not used for part numbers with P)	O
19	A01	I	44	-REG -DMACK (not used for part numbers with P)	I
20	A00	I	45	BVD2 -SPKR -DASP	I/O
21	D00	I/O	46	BVD1 -STSCHG -PDIAG	I/O
22	D01	I/O	47	D08	I/O
23	D02	I/O	48	D09	I/O
24	WP -IOIS16	O	49	D10	I/O
25	-CD2	O	50	GND	Ground

Legend: "-" = Low active

## 1.4 Signal Descriptions

Table 4: CF Card Signal Descriptions

Signal Name	Type	Pin Number	Description
BVD2 (PC Card Memory Mode)	I/O	45	This output line is always driven to a high state in Memory Mode since a battery is not required for this product.
-SPKR (PC Card I/O Mode)			This output line is always driven to a high state in I/O Mode since this product produces no audio.
-DASP (True IDE Mode)			In the True IDE Mode, this input/output is the Disk Active/Slave Present signal in the Master/Slave handshake protocol.
-CD1, -CD2 (PC Card Memory Mode)	I/O	26, 25	These Card Detect pins are connected to ground on the card. They are used by the host to determine that the card is fully inserted into the socket.
-CD1, -CD2 (PC Card I/O Mode)			This signal is the same as Memory Mode.
-CD1, -CD2 (True IDE Mode)			These signals are not used in IDE Mode.
D15-D00 (PC Card Memory Mode)	I/O	31, 30, 29, 28, 27, 49, 48, 47, 6, 5, 4, 3, 2, 23, 22, 21	These lines carry the data, commands, and host and the controller. D00 is the LSB of the LSB of the Odd Byte of the Word.
D15-D00 PC Card I/O Mode			This signal is the same as the PC Card Memory Mode signal.
D15-D00 (True IDE Mode)			In True IDE Mode, all Task File operations occur in byte mode on the low order bus D00-D07 while all data transfers are 16 bit using D00-D15.
-IOWR (PC Card Memory Mode)	I	35	This signal is not used in this mode.
-IOWR (PC Card I/O Mode)			The I/O Write strobe pulse is used to clock I/O data onto the data bus and into the controller registers. The clocking occurs on the negative to positive edge of the signal (trailing edge).
-IOWR (True IDE Mode)			In True IDE Mode, this signal has the same function as in PC Card I/O Mode.
-IORD (PC Card Memory Mode)	I	34	This signal is not used in this mode.
-IORD (PC Card I/O Mode)			This is an I/O Read strobe generated by the host. This signal gates I/O data onto the bus from the CF Card.
-IORD (True IDE Mode)			In True IDE Mode, this signal has the same function as in PC Card I/O Mode.
-WE (PC Card Memory Mode)	I	36	This is a signal driven by the host and used for strobing memory write data into the registers. It is also used for writing the configuration registers.
-WE (PC Card I/O Mode)			In PC Card I/O Mode, this signal is used for writing the configuration registers.
-WE (True IDE Mode)			In True IDE Mode, this input signal is not used and should be connected to VCC.
-OE (PC Card Memory Mode)	I	9	This is an Output Enable strobe generated by the host interface. It is used to read data from the CF Card in PC Card Memory Mode and to read the CIS and configuration registers.

Signal Name	Type	Pin Number	Description
-OE (PC Card I/O Mode)			In PC Card I/O Mode, this signal is used to read the CIS and configuration registers.
-ATASEL (True IDE Mode)			To enable True IDE Mode, this input should be grounded by the host.
RDY/-BSY (PC Card Memory Mode)	O	37	In Memory Mode, this signal is set high when the CF Card is ready to accept a new data transfer operation and held low when the CF Card is busy. The host must provide a pull-up resistor. At power up and at reset, the RDY/-BSY signal is held low (busy) until the CF Card completes its power up or reset function. No access of any type should be made to the CF Card during this time. The RDY/-BSY signal is held high (disabled from being busy) when the CF Card is powered up with RESET continuously disconnected or asserted high.
-IREQ (PC Card I/O Mode)			After the CF Card has been configured for I/O operation, this signal is used as the active low interrupt request. This line is strobed low to generate a pulse mode interrupt or held low for a level mode interrupt.
INTRQ (True IDE Mode)			In True IDE Mode, this signal is the active high interrupt request to the host.
A10-A0 (PC Card Memory Mode)	I	8, 10, 11, 12, 14, 15, 16, 17, 18, 19, 20	These address lines along with the -REG signal are used to select the following: the I/O port address registers within the CF Card, the memory mapped port address registers within the CF Card, a byte in the CIS and the Configuration Control and Status Registers.
A10-A0 (PC Card I/O Mode)			This signal is the same as the PC Card Memory Mode signal.
A2-A0 (True IDE Mode)		18, 19, 20	In True IDE Mode only, A2:A0 are used to select the one of eight registers in the Task File. The remaining address lines should be grounded.
-CE1, -CE2 (PC Card Memory Mode Card Enable)	I	7, 32	These input signals are used both to select the CF Card and to indicate to the CF Card whether a byte or a word operation is being performed. -CE2 always accesses the odd byte of the word. -CE1 accesses the even byte or the odd byte of the word depending on A0 and -CE2. A multiplexing scheme based on A0, -CE1, -CE2 allows 8-bit hosts to access all data on D0-D7.
-CE1, -CE2 (PC Card I/O Mode) Card Enable			This signal is the same as the PC Card Memory Mode signal.
-CS0, -CS1 (True IDE Mode)			In the True IDE Mode, -CS0 is the chip select for the task file registers while -CS1 is used to select the Alternate Status Register and the CF Card Control Register.
-CSEL (PC Card Memory Mode)	I	39	This signal is not used for this mode.
-CSEL (PC Card I/O Mode)			This signal is not used for this mode.
-CSEL (True IDE Mode)			This internally pulled up signal is used to configure the card as a Master or Slave. When the pin is grounded, the card is configured as a Master. When the pin is open, the card is configured as a Slave.
-REG (PC Card Memory Mode) Attribute Memory Select	I	44	This signal distinguishes between accesses to Common Memory (high) and Register Attribute Memory (low).



Signal Name	Type	Pin Number	Description
-REG (PC Card I/O Mode)			The signal must also be active (low) during I/O Cycles when the I/O address is on the bus.
-DMACK (not used for part numbers with P) (True IDE Mode)			In True IDE Mode this input signal is used by host in response to DMARQ to initiate DMA transfers.
WP (PC Card Memory Mode) Write Protect	O	24	The CF Card does not have a write protect switch; therefore, this signal is held low after the completion of the reset initialization sequence.
-IOIS16 (PC Card I/O Mode)			A low signal indicates that a 16 bit or odd byte only operation can be performed at the addressed port.
-IOCS16 (True IDE Mode)			Not defined in IDE Mode.
-INPACK (PC Card Memory Mode)	O	43	This signal is not used in this mode.
-INPACK (PC Card I/O Mode) Input Acknowledge			The Input Acknowledge signal is asserted by the CF Card when it is selected and responding to an I/O read cycle at the address that is on the bus. The host uses this signal to control the enable of any input data buffers between the CF Card and the host's CPU.
DMARQ (Not used for part numbers with P) (True IDE Mode)			In True IDE Mode this signal is asserted by the CF Card when it is ready to transfer data to/from the host. Data direction is controlled by -IORD and -IOWR. This signal is used in a handshake manner with -DMACK.
BVD1 (PC Card Memory Mode)	I/O	46	This signal is asserted high as since a battery is not used with this product.
-STSCHG (PC Card I/O Mode) Status Changed			This signal is asserted low to alert the host to changes in the RDY/-BSY and Write Protect states. Its use is controlled by the Configuration and Status Register.
-PDIAG (True IDE Mode)			In True IDE Mode, this input/output signal is the Pass Diagnostic signal in the Master/Slave handshake protocol.
-WAIT (PC Card Memory Mode)	O	42	This signal is not used by the CF Card, and is pulled up to VCC through a 4.7K ohm resistor.
-WAIT (PC Card I/O Mode)			This signal is not used by the CF Card, and is pulled up to VCC through a 4.7K ohm resistor.
IORDY (True IDE Mode)			This signal is not used by the CF Card, and is pulled up to VCC through a 4.7K ohm resistor.
GND (PC Card Memory Mode)	GND	1, 50	Ground
GND (PC Card I/O Mode)			Ground
GND (True IDE Mode)			Ground
VCC (PC Card Memory Mode)	VCC	13, 38	+5 V or 3.3V power
VCC (PC Card I/O Mode)			+5 V or 3.3V power
VCC (True IDE Mode)			+5 V or 3.3V power
RESET (PC Card Memory Mode)	I	41	When RESET is high, this signal resets the CF Card. The CF Card is reset only at power up if this signal is left high or open from power-up. The CF Card can also be reset when the soft reset bit in the Configuration Option Register is set.

Signal Name	Type	Pin Number	Description
RESET (PC Card I/O Mode)			This signal is the same as the PC Card Memory Mode signal.
-RESET (True IDE Mode)			In the True IDE Mode this input pin is the active low hardware reset from the host.
-VS1 -VS2 (PC Card Memory Mode)	O	33, 40	-VS1 is grounded so that the card CIS can be read at 3.3 volts. -VS2 is reserved for a secondary voltage and is not connected..
-VS1 -VS2 (PC Card I/O Mode)			This signal is the same for all models.
-VS1 -VS2 (True IDE Mode)			This signal is not used in IDE Mode.

## 1.5 Performance

Table 5: CF Card Read/Write Performance

Parameter	Value
Data transfer rate to/from host	16.7 MBytes/s (burst)
Sustained read	up to 10 MBytes/s
Sustained write	up to 7 MBytes/s

## 1.6 CHS Parameters

Table 6: CHS Parameters per capacity

Capacity	Cylinder (C) (standard)	Cylinder (C) (for part number with S suffix)	Head (H)	Sectors/Track (S)
128MB	980	924	8	32
256MB	980	924	16	32
512MB	993	939	16	63
1GB	1,986	1,878	16	63
2GB	3,970	3,756	16	63
4GB	7,964	7,535	16	63
8GB	16,062	15,093	16	63
16GB	31,760	-	16	63

## 1.7 Standards Compliance

STEC products specified in this document are certified for compliance with the following industry standards:

- CFA v4.0, PCMCIA v7.0
- UL 950
- CE, and FCC Class B & D
- RoHS

### 1.7.1 CE and FCC Class B & D

The STEC products specified in this document meet the following requirements and limits of the European Standards:

- Class B requirements of the following European Standard:  
EN 55022: 1998 – “Information technology equipment – Radio disturbance characteristics – Limits and methods of measurement”
- Class D limits of the following European Standards:  
EN 61000-3-2 “Electromagnetic compatibility (EMC) Part 3-2: Limits – Limits for harmonic current emissions (equipment input current up to and including 16 A per phase)”  
EN 61000-3-3: 1995 – “Part 3: Limits – Section 3: Limitation of voltage fluctuations and flicker in low-voltage supply systems for equipment with rated current  $\leq 16A$ ”  
EN 55024 – “Information technology equipment – Immunity characteristics – Limits and methods of measurement”

### 1.7.2 RoHS

STEC certifies that its products do not contain any of the restricted substances as stated below and are in compliance with RoHS EU directive 2002/95/EC, specifically:

- Mercury (Hg)
- Cadmium Cd)
- Chromium VI (Cr +6)
- Polybrominated biphenyl (PBB)
- Polybrominated biphenyl ether (PBDE)
- Lead (Pb)

Materials used in the STEC’s products are limited to the following:

- Steel, Nylon 6/6, PCB laminate
- Copper, Gold, Nickel
- Silicon on ICs and Components
- Polyester on Labels

## 2.0 Environmental Specifications

### 2.1 Recommended Operating Conditions

Table 7: CF Card Recommended Operating Conditions

Parameter	Symbol	Min	Typ	Max	Unit
Commercial Operating Temperature	Ta	0	25	70	°C
Industrial Operating Temperature	Ta	-40	-	85	°C
VCC voltage 5.0	VCC5	4.75	5.0	5.25	V
VCC voltage 3.3	VCC3.3	3.18	3.3	3.465	V

### 2.2 Reliability

Table 8: CF Card Endurance & Data Reliability

Parameter	Value
Endurance	2,000,000 Write/Erase Cycles
Data reliability	1 in 10 <sup>14</sup> bits, read
Data retention	10 years

### 2.3 Shock, Vibration, and Humidity

Table 9: CF Card Shock, Vibration & Humidity

Parameter	Value
Shock	1.5K G peak, 0.5ms pulse duration, five (5) pulses per each of six (6) directions (per JEDEC JESD22 standard, method B110)
Vibration	20 G peak, 20Hz-2000Hz, 4 cycles per direction (per JEDEC JESD22 standard, method B103)
Humidity	85°C 85% RH, 500 hrs

### 3.0 Electrical Specifications

#### 3.1 Absolute Maximum Ratings

Table 10: CF Card Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Voltage	Vin, Vout	-0.5 to VCC +0.5	V
Storage temperature range	Tstg	-65 to +150	°C

#### 3.2 DC Characteristics

Measurements at Recommended Operating Conditions unless otherwise specified.

Table 11: CF Card DC Characteristics

Symbol	Parameter	Min	Max	Unit	Notes
VIL	Input LOW Voltage	-0.3	+0.8	V	VCC=3.3V or 5.0V
VIH	Input HIGH Voltage	2.0	VCC +0.3	V	VCC=3.3V or 5.0V
VOL3.3	Output LOW Voltage 3.3		0.45	V	VCC=3.3V
VOL5	Output LOW Voltage 5		0.8		VCC=5.0V
VOH	Output HIGH Voltage	2.4		V	VCC=3.3V or 5.0V
ICCSB	Standby Mode		2	mA	ICC at VCC=3.3V or 5.0V
ICC	Operating Current		75	mA	ICC at VCC=3.3V or 5.0V; Operating current measured with 2-way interleaving.
ILI	Input Leakage Current		10	µA	VCC=3.3V or 5.0V
ILO3.3	Output Leakage Current 3.3		1	µA	VCC=3.3V
ILO5	Output Leakage Current 5		2	µA	VCC= 5.0V
CI/O	Input/output Capacitance		25	pF	VCC=3.3V or 5.0V

### 3.3 AC Characteristics

Measurements at Recommended Operating Conditions, unless otherwise specified.

#### 3.3.1 PC Card Memory Mode Attribute Memory Read

Table 12: PC Card Memory Mode Attribute Memory Read AC Characteristics

Parameter	Symbol	IEEE Symbol	Min (ns)	Max (ns)
Read Cycle Time	tc(R)	tAVAV	250	
Address Access Time	ta(A)	tAVQV		250
Card Enable Access Time	ta(CE)	tELQV		250
Output Enable Access Time	ta(OE)	tGLQV		125
Output Disable Time from -CE	tdis(CE)	tEHQZ		100
Output Disable Time from -OE	tdis(OE)	tGHQZ		100
Address Setup Time	tsu(A)	tAVGL	30	
Output Enable Time from -CE	ten(CE)	tELQNZ	5	
Output Enable Time from -OE	ten(OE)	tGLQNZ	5	
Data Valid from Address Change	tv(A)	tAXQX	0	
Address Hold Time	th(A)	—	20	
-CE Setup Time	tsu(CE)	—	0	
-CE Hold Time	th(CE)	—	20	

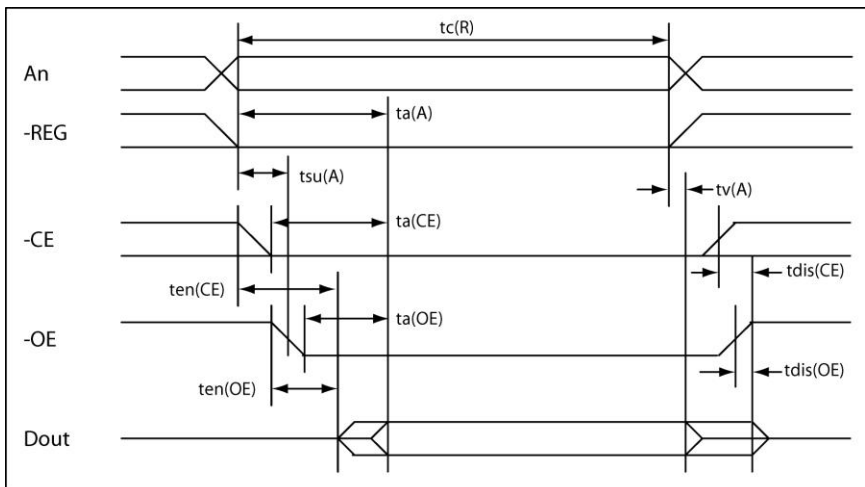


Figure 4: PC Card Memory Mode Attribute Memory Read Timing Diagram

3.3.2 PC Card Memory Mode Attribute Memory Write

Table 13: PC Card Memory Mode Attribute Memory Write AC Characteristics

Parameter	Symbol	IEEE Symbol	Min (ns)	Max (ns)
Write Cycle Time	tc(W)	tAVAV	250	
Write Pulse Width	tw(WE)	tWLWH	150	
Address Setup Time	tsu(A)	tAVWL	30	
Address Setup Time (-WE)	tsu(A-WEH)	—	180	
-CE Setup Time (-WE)	tsu(CE-WEH)	—	180	
Data Setup Time (-WE)	tsu(D-WEH)	tDVWH	80	
Data Hold Time	th(D)	tWMDX	30	
Write Recovery Time	trec(WE)	tWMAX	30	
Output Disable Time (-WE)	tdis(WE)	—		100
Output Disable Time (-OE)	tdis(OE)	—		100
Output Enable Time (-WE)	ten(WE)	—	5	
Output Enable Time (-OE)	ten(OE)	—	5	
Output Enable Setup Time (-WE)	tsu(OE-WE)	—	10	
Output Enable Hold Time (-WE)	th(OE-WE)	—	10	
-CE Setup Time	tsu(CE)	—	0	
-CE Hold Time	th(CE)	—	20	

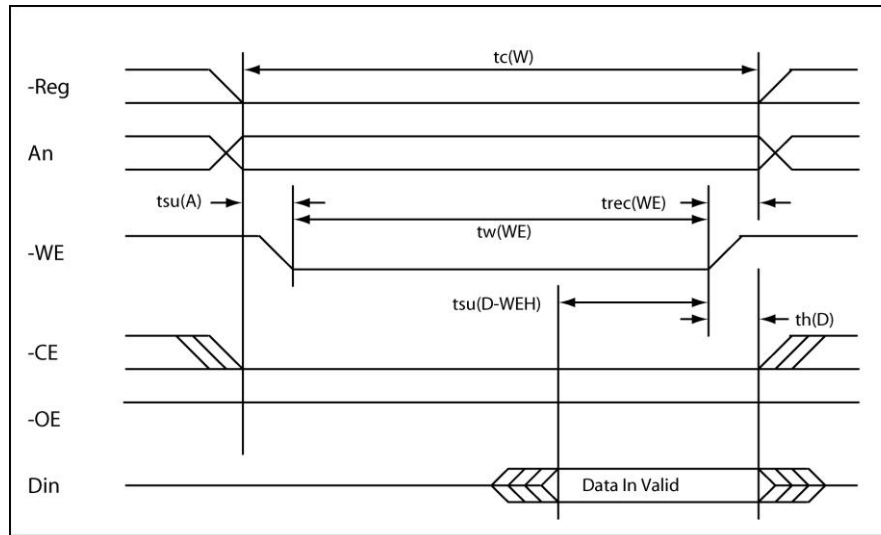


Figure 5: PC Card Memory Mode Attribute Memory Write Timing Diagram

### 3.3.3 PC Card Memory Mode Common Memory Read

Table 14: PC Card Memory Mode Common Memory Read AC Characteristics

Parameter	Symbol	IEEE Symbol	250 ns Cycle Time Mode	120 ns Cycle Time Mode	100 ns Cycle Time Mode	80 ns Cycle Time Mode
Output Enable Access Time (max)	ta(OE)	tGLQV	125	60	50	45
Output Disable Time from OE (max)	t <sub>dis</sub> (OE)	tGHQZ	100	60	50	45
Address Setup Time (min)	tsu(A)	tAVGL	30	15	10	10
Address Hold Time (min)	th(A)	tGHAX	20	15	15	10
CE Setup before OE (min)	tsu(CE)	tELGL	0	0	0	0
CE Hold following OE (min)	th(CE)	tGHEH	20	15	15	10
Wait Delay Falling from OE (max)	tv(WT-OE)	tGLWTV	35	35	35	N/A
Data Setup for Wait Release (max)	tv(WT)	tQVWTH	0	0	0	N/A
Wait Width Time (max)	tw(WT)	tWTLWTH	350	350	350	N/A

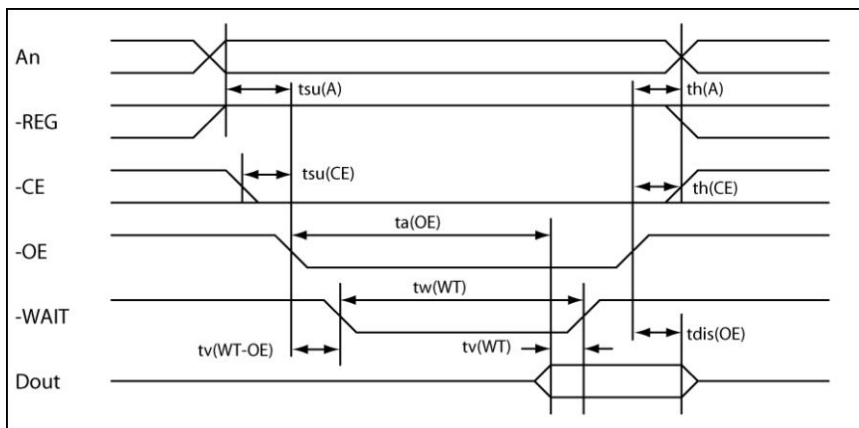


Figure 6: PC Card Memory Mode Common Memory Read Timing Diagram



3.3.4 PC Card Memory Mode Common Memory Write

Table 15: PC Card Memory Mode Common Memory Write AC Characteristics

Parameter	Symbol	IEEE Symbol	250 ns Cycle Time Mode	120 ns Cycle Time Mode	100 ns Cycle Time Mode	80ns Cycle Time Mode
Data Setup before WE (min)	tsu (D-WEH)	tDVWH	80	50	40	30
Data Hold following WE (min)	th(D)	tWMDX	30	15	10	10
WE Pulse Width (min)	tw(WE)	tWLWH	150	70	60	55
Address Setup Time (min)	tsu(A)	tAVWL	30	15	10	10
CE Setup before WE (min)	tsu(CE)	tELWL	0	0	0	0
Write Recovery Time (min)	trec(WE)	tWMAX	30	15	15	15
Address Hold Time (min)	th(A)	tGHAX	20	15	15	15
CE Hold following WE (min)	th(CE)	tGHEH	20	15	15	10
Wait Delay Falling from WE (max)	tv(WT-WE)	tWLWTV	35	35	35	N/A
WE High from Wait Release (min)	tv(WT)	tWTHWH	0	0	0	N/A
Wait Width Time (max)	tw(WT)	wWTLWTH	350	350	350	N/A

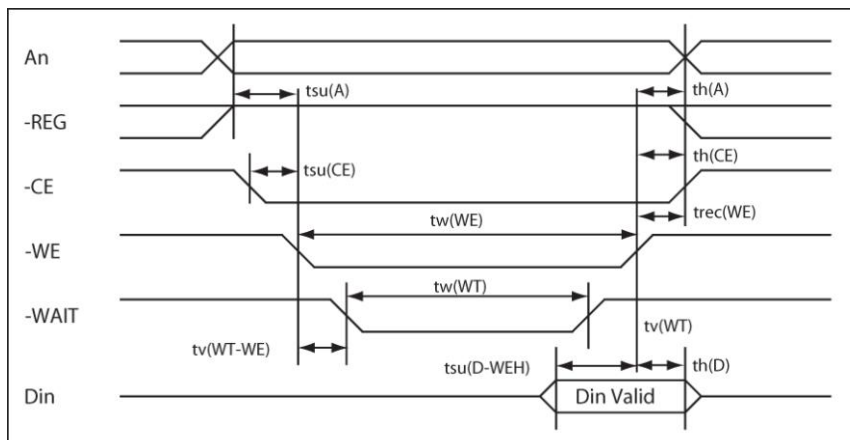


Figure 7: PC Card Memory Mode Common Memory Write Timing Diagram

3.3.5 PC Card I/O Mode Read AC Characteristics

Table 16: PC Card I/O Mode Read AC Characteristics

Parameter	Symbol	IEEE Symbol	250 ns Cycle Time Mode	120 ns Cycle Time Mode	100 ns Cycle Time Mode	80 ns Cycle Time Mode
Data Delay after -IORD (max)	td(IORD)	tIGLQV	100	50	50	45
Data Hold following -IORD (min)	th(IORD)	tIGHQX	0	5	5	5
-IORD Width Time (min)	tw(IORD)	tIGLIGH	165	70	65	55
Address Setup before -IORD (min)	tsuA(IORD)	tAVIGL	70	25	25	15
Address Hold following -IORD (min)	thA(IORD)	tIGHAX	20	10	10	10
-CE Setup before -IORD (min)	tsuCE(IORD)	tELIGL	5	5	5	5
-CE Hold following -IORD	thCE(IORD)	tIGHEH	20	10	10	10
-REG Setup before -IORD (min)	tsuREG(IORD)	tRGLIGL	5	5	5	5
-REG Hold following -IORD (min)	thREG(IORD)	tIGHRGH	0	0	0	0

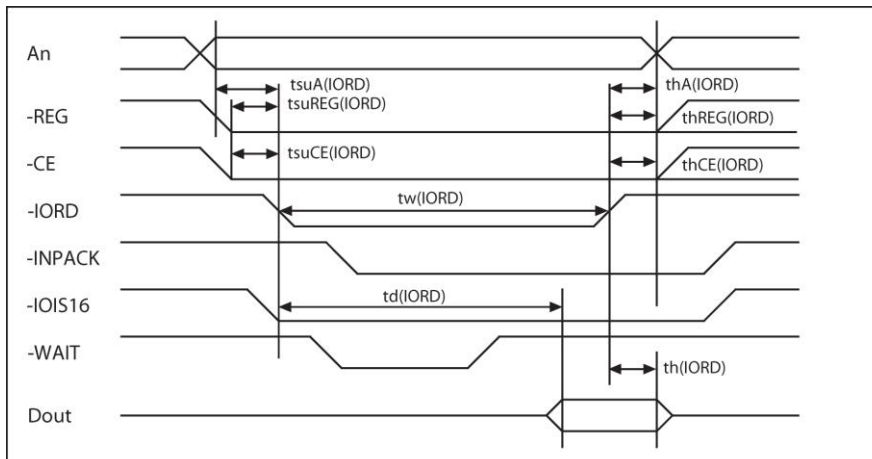


Figure 8: PC Card I/O Mode Read Timing Diagram

3.3.6 PC Card I/O Mode Write AC Characteristics

Table 17: PC Card I/O Mode Write AC Characteristics

Parameter	Symbol	IEEE Symbol	250 ns Cycle Time Mode	120 ns Cycle Time Mode	100 ns Cycle Time Mode	80 ns Cycle Time Mode
Data Setup before -IOWR (min)	tsu(IOWR)	tDVIWH	60	20	20	15
Data Hold following -IOWR (min)	th(IOWR)	tIWHDX	30	10	5	5
-IOWR Width Time (min)	tw(IOWR)	tIWLWH	165	70	65	55
Address Setup before -IOWR (min)	tsuA(IOWR)	tAVIWL	70	25	25	15
Address Hold following -IOWR (min)	thA(IOWR)	tIWHAX	20	20	10	10
-CE Setup before -IOWR (min)	tsuCE(IOWR)	tELIWL	5	5	5	5
-CE Hold following -IOWR (min)	thCE(IOWR)	tIWHEH	20	20	10	10
-REG Setup before -IOWR (min)	tsuREG(IOWR)	tRGLIWL	5	5	5	5
-REG Hold following -IOWR (min)	thREG(IOWR)	tIWHRGH	0	0	0	0

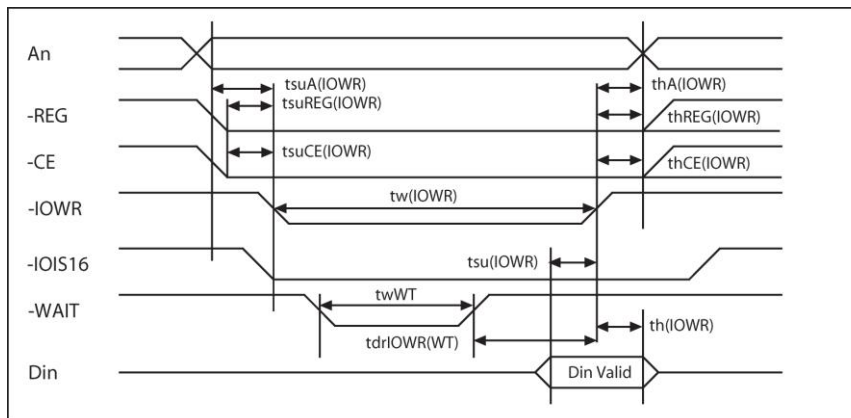


Figure 9: PC Card I/O Mode Read Timing Diagram

### 3.3.7 True IDE Mode Register Access

Table 18: True IDE Mode Register Access AC Characteristics

Parameter	Symbol	Mode0	Mode1	Mode2	Mode3	Mode4	Mode5	Mode6	Unit
Cycle time (min)	t0	600	383	330	180	120	100	80	ns
Address valid to -IORD/-IOWR (min) setup	t1	70	50	30	30	25	15	10	ns
-IORD/-IOWR pulse width 8bit (min)	t2	290	290	290	80	70	65	55	ns
-IORD/-IOWR recovery time (min)	t2i	—	—	—	70	25	25	20	ns
-IOWR data setup (min)	t3	60	45	30	30	20	20	15	ns
-IOWR data hold (min)	t4	30	20	15	10	10	5	5	ns
-IORD data setup (min)	t5	50	35	20	20	20	15	10	ns
-IORD data hold (min)	t6	5	5	5	5	5	5	5	ns
-IORD data tristate (max)	t6z	30	30	30	30	30	20	20	ns
Addresses valid to -IOCS16 assert. (max)	t7	90	50	40	N/A	N/A	N/A	N/A	ns
Address valid to -IOCS16 release (max)	t8	60	45	30	N/A	N/A	N/A	N/A	ns
-IORD/-IOWR to address valid hold	t9	20	15	10	10	10	10	10	ns

### 3.3.8 True IDE Mode PIO Access

Table 19: True IDE Mode PIO Access AC Characteristics

Parameter	Symbol	Mode0	Mode1	Mode2	Mode3	Mode4	Mode5	Mode6	Unit
Cycle time (min)	t0	600	383	330	180	120	100	80	ns
Address valid to -IORD/-IOWR (min) setup	t1	70	50	30	30	25	15	10	ns
-IORD/-IOWR pulse width 8bit (min)	t2	290	290	290	80	70	65	55	ns
-IORD/-IOWR recovery time (min)	t2i	—	—	—	70	25	25	20	ns
-IOWR data setup (min)	t3	60	45	30	30	20	20	15	ns
-IOWR data hold (min)	t4	30	20	15	10	10	5	5	ns
-IORD data setup (min)	t5	50	35	20	20	20	15	10	ns
-IORD data hold (min)	t6	5	5	5	5	5	5	5	ns
-IORD data tristate (max)	t6z	30	30	30	30	30	20	20	ns
Addresses valid to -IOCS16 assert. (max)	t7	90	50	40	N/A	N/A	N/A	N/A	ns
Address valid to -IOCS16 release	t8	60	45	30	N/A	N/A	N/A	N/A	ns
-IORD/-IOWR to address valid hold	t9	20	15	10	10	10	10	10	ns

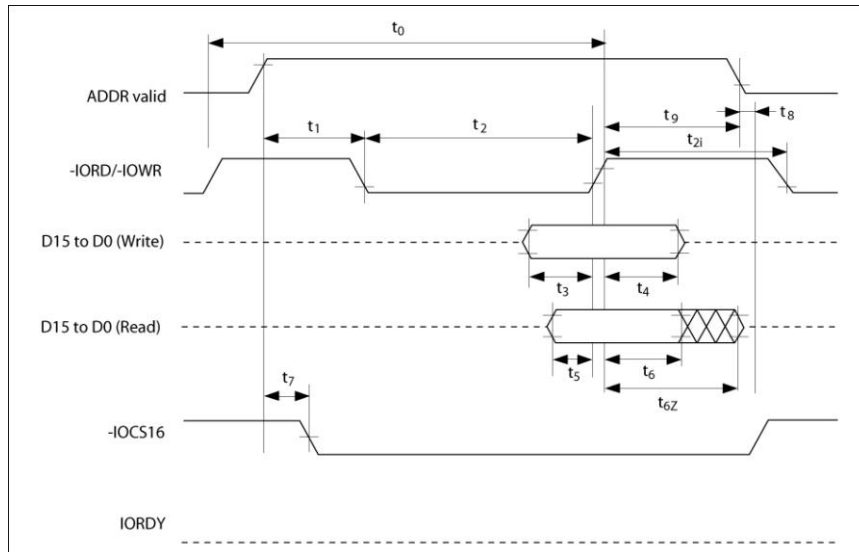


Figure 10: True IDE Mode PIO Access Timing Diagram

3.3.9 True IDE Mode Multiword DMA (not used for part numbers with P)

Table 20: True IDE Mode Multiword DMA AC Characteristics

Parameter	Symbol	Mode 0	Mode 1	Mode 2	Mode 3	Mode 4	Unit
Cycle time (min)	$t_0$	480	150	120	100	80	ns
-IORD/-IOWR Asserted Pulse (min)	$t_D$	215	80	70	65	55	ns
-IORD data access (max)	$t_E$	150	60	50	50	45	ns
-IORD data hold (min)	$t_F$	5	5	5	5	5	ns
-IORD/-IOWR data setup (min)	$t_G$	100	30	20	15	10	ns
-IOWR data hold (min)	$t_H$	20	15	10	5	5	ns
DMACK to -IORD/-IOWR setup (min)	$t_I$	0	0	0	0	0	ns
-IORD/-IOWR to DMACK hold (min)	$t_J$	20	5	5	5	5	ns
-IORD negated pulse width (max)	$t_{KR}$	50	50	25	25	20	ns
-IOWR negated pulse width (min)	$t_{KW}$	215	50	25	25	20	ns
-IORD to DMARQ delay (max)	$t_{LR}$	120	40	35	35	35	ns
-IOWR to DMARQ delay (max)	$t_{LW}$	40	40	35	35	35	ns

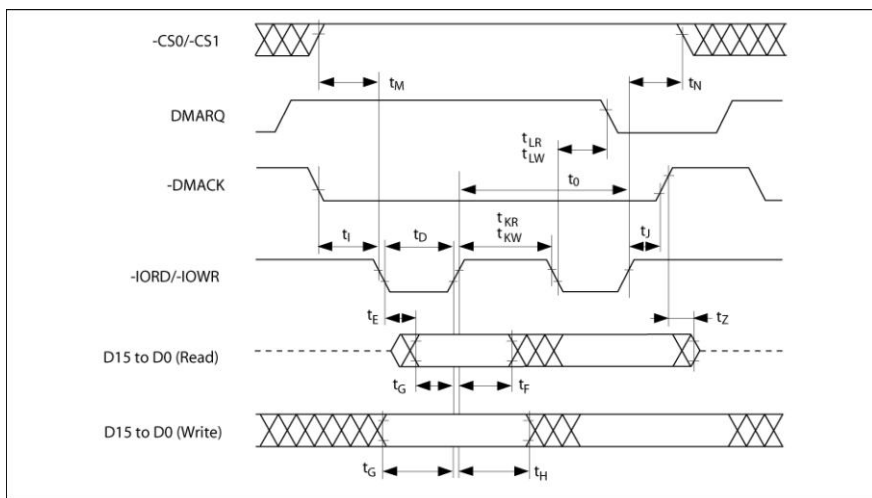


Figure 11: True IDE Mode Multiword DMA Timing Diagram

3.4 PC Card Memory and I/O Modes Power Up to READY and RESET to READY

Table 21: Power Up to READY and RESET to READY AC Characteristics

Parameter	Symbol	Capacity	Min	Typ	Max	Unit
Power up to READY	$t_{rdy}$	128MB	0.069	70	71	ms
		256MB	0.073	73.8	74.1	ms
		512MB	0.0702	70.3	70.3	ms
		1GB	0.069	69.2	69.5	ms
RESET to READY	$t_{rdy}$	128MB	0.048	48	48	ms
		256MB	0.0521	52.1	52.2	ms
		512MB	0.0483	48.3	48.5	ms
		1GB	0.0469	47.1	47.3	ms
Minimum Rec. Reset Width	$T_w(\text{reset})$	-	0.200	-	-	ms

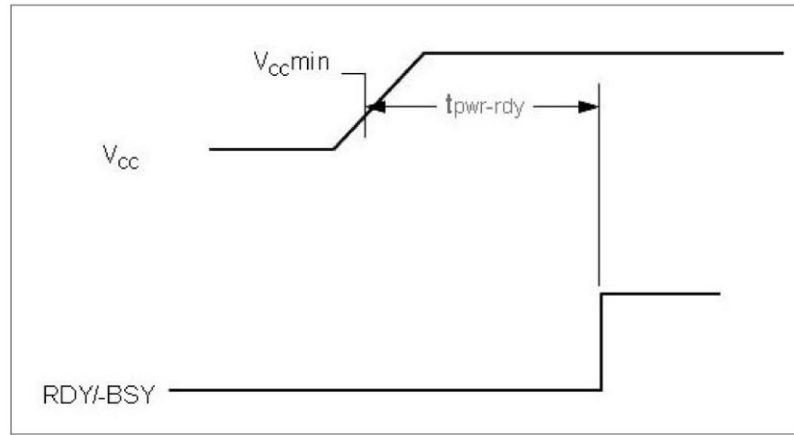


Figure 12: Power Up to RDY Timing

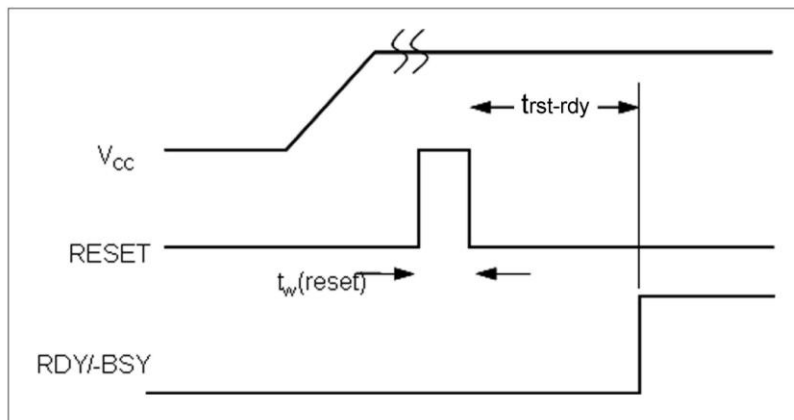


Figure 13: RESET to RDY Timing



## 4.0 Host Access Specification

### 4.1 Task File Register and Byte/Word/Odd-Byte Mode Mappings

Please refer to the CF Card standards for complete details on:

- Task File Register mapping for the interface modes
- Byte/Word/Odd-byte mode mapping within each of the interface modes

### 4.2 Host Access Interface Modes

The host can access the CF Card by using the following interface modes with the Task Registers:

1. *PC Card Memory Mode, Attribute Memory*  
The Card Information Structure (CIS) in Attribute Memory can be accessed by Byte/Word/Odd-byte modes in PC Card Memory Mode. The -REG signal must be asserted when accessing Attribute Memory. The CF Card is mapped to PC Card Memory Mode by the Index bits in the Configuration Option Register. An example of a CIS is listed in 4.3, *Card Information Structure (CIS)*.
2. *PC Card Memory Mode, Common Memory*  
Common Memory can be accessed in the Byte/Word/Odd Byte modes in PC Card Memory Mode. The -REG signal must be de-asserted when accessing the Common Memory. The CF Card is mapped to PC Card Memory Mode by the Index bits in the Configuration Option Register
3. *PC Card I/O Mode*  
The CF Card can be accessed by Byte/Word/Odd Byte modes in PC Card I/O Mode. The CF Card is mapped to PC Card I/O Mode by the Index bits in the Configuration Option Register. The Index bits also select Contiguous I/O, Primary I/O, or Secondary I/O mapping when using the PC Card I/O Mode.
4. *True-IDE mode*  
The CF Card is configured in a True IDE Mode of operation when the -ATASEL input signal is asserted GND by the host at power up. In the True IDE Mode, Attribute Registers are not accessible from the host. The Data Register is accessed in word (16-bit) mode at power up. The CF Card permits 8-bit accesses if the host issues a Set Feature Command to put the CF Card in 8-bit mode. Parameter information that the CF Card uses in True IDE mode is returned when the Identify Drive command (ECh) is invoked. Refer to 4.4 *Identify Drive Parameter Information* for an example.

### 4.3 Card Information Structure (CIS)

The CF Card uses a Card Information Structure (CIS) as summarized below:

1. 0000: Code 01, link 03  
D9 01 FF  
Tuple CISTPL\_DEVICE (01), length 3 (03) at offset 0
  - Device type is FUNCSPEC
  - Device speed is 250ns
  - Write protect switch is not in control
  - Device size is 2K bytes
2. 0005: Code 1C, link 04  
03 D9 01 FF  
Tuple CISTPL\_DEVICE\_OC (1C), length 4 (04) at offset 5
  - Device conditions: minimum cycle with WAIT at Vcc = 3.3V
  - Device type is FUNCSPEC
  - Device speed is 250ns
  - Write protect switch is not in control
  - Device size is 2K bytes
3. 000B: Code 18, link 02  
DF 01  
Tuple CISTPL\_JEDEC\_C (18), length 2 (02) at offset B
  - Device 0 JEDEC id: Manufacturer DF, ID 01
4. 000F: Code 20, link 04  
4D 01 00 01  
Tuple CISTPL\_MANFID (20), length 4 (04) at offset F
  - Manufacturer # 0x014D hardware rev 1.00
5. 0015: Code 15, link 13  
04 01 53 54 49 00 46 6C 61 73 68 20 37 2E 30 2E 30 00 FF  
Tuple CISTPL\_VERS\_1 (15), length 19 (13) at offset 15
  - Major version 4, minor version 1
  - Product Information: "STI" (Manufacturer) "Flash X.Y.Z" (Product Name)
6. 002A: Code 21, link 02  
04 /xx 01  
Tuple CISTPL\_FUNCID (21), length 2 (02) at offset 2A
  - Function code 04 (Fixed), or xx (Removable), system init 01
7. 002E: Code 22, link 02  
01 01  
Tuple CISTPL\_FUNCE (22), length 2 (02) at offset 2E
  - This is an PC Card ATA Disk

8. 0032: Code 22, link 03  
02 0C 0F  
Tuple CISTPL\_FUNCE (22), length 3 (03) at offset 32
  - Vpp is not required
  - This is a silicon device
  - Identify Drive Model/Serial Number is guaranteed unique
  - Low-Power Modes supported: Sleep Standby Idle
  - Drive automatically minimizes power
  - All modes include 3F7 or 377
  - Index bit is not supported
  - -IOIS16 is unspecified in Twin configurations
9. 0037: Code 1A, link 05  
01 03 00 02 0F  
Tuple CISTPL\_CONFIG (1A), length 5 (05) at offset 37
  - Last valid configuration index is 3
  - Configuration Register Base Address is 200
  - Configuration Registers Present:
    - Configuration Option Register at 200
    - Card Configuration and Status Register at 202
    - Pin Replacement Register at 204
    - Socket and Copy Register at 206
10. 003E: Code 1B, link 08  
C0 C0 A1 01 55 08 00 20  
Tuple CISTPL\_CFTABLE\_ENTRY (1B), length 8 (08) at offset 3E
  - Configuration Table Index is 00 (default)
  - Interface type is Memory
  - BVDs not active, WP not active, RdyBsy active
  - Wait signal support required
  - Vcc Power Description: Nom V = 5.0 V
  - Map 2048 bytes of memory to CF Card address 0
  - Miscellaneous Features: Max Twins 0, -Audio, -ReadOnly, +PowerDown
11. 0048: Code 1B, link 06  
00 01 21 B5 1E 4D  
Tuple CISTPL\_CFTABLE\_ENTRY (1B), length 6 (06) at offset 48
  - Configuration Table Index is 00
  - Vcc Power Description: Nom V = 3.30 V, Peak I = 45.0 mA

12. 0050: Code 1B, link 0A  
C1 41 99 01 55 64 F0 FF FF 20  
Tuple CISTPL\_CFTABLE\_ENTRY (1B), length 10 (0A) at offset 50 10 (0A) at offset 50
  - Configuration Table Index is 01 (default)
  - Interface type is I/O
  - BVDs not active, WP not active, RdyBsy active
  - Wait signal support not required
  - Vcc Power Description: Nom V = 5.0 V
  - Decode 4 I/O lines, bus size 8 or 16
  - IRQ may be shared, pulse and level mode interrupts are supported
  - Interrupts in mask FFFF are supported
  - Miscellaneous Features: Max Twins 0, -Audio, -ReadOnly, +PowerDown
13. 005C: Code 1B, link 06  
01 01 21 B5 1E 4D  
Tuple CISTPL\_CFTABLE\_ENTRY (1B), length 6 (06) at offset 5C
  - Configuration Table Index is 01
  - Vcc Power Description: Nom V = 3.30 V, Peak I = 45.0 mA
14. 0064: Code 1B, link 0F  
C2 41 99 01 55 EA 61 F0 01 07 F6 03 01 EE 20  
Tuple CISTPL\_CFTABLE\_ENTRY (1B), length 15 (0F) at offset 64
  - Configuration Table Index is 02 (default)
  - Interface type is I/O
  - BVDs not active, WP not active, RdyBsy active
  - Wait signal support not required
  - Vcc Power Description: Nom V = 5.0 V
  - Decode 10 I/O lines, bus size 8 or 16
  - I/O block at 01F0, length 8
  - I/O block at 03F6, length 2
  - IRQ may be shared, pulse and level mode interrupts are supported
  - Only IRQ14 is supported
  - Miscellaneous Features: Max Twins 0, -Audio, -ReadOnly, +PowerDown
15. 0075: Code 1B, link 06  
02 01 21 B5 1E 4D  
Tuple CISTPL\_CFTABLE\_ENTRY (1B), length 6 (06) at offset 75
  - Configuration Table Index is 02
  - Vcc Power Description: Nom V = 3.30 V, Peak I = 45.0 mA

16. 007D: Code 1B, link 0F  
C3 41 99 01 55 EA 61 70 01 07 76 03 01 EE 20  
Tuple CISTPL\_CFTABLE\_ENTRY (1B), length 15 (0F) at offset 7D
  - Configuration Table Index is 03 (default)
  - Interface type is I/O
  - BVDs not active, WP not active, RdyBsy active
  - Wait signal support not required
  - Vcc Power Description: Nom V = 5.0 V
  - Decode 10 I/O lines, bus size 8 or 16
  - I/O block at 0170, length 8
  - I/O block at 0376, length 2
  - IRQ may be shared, pulse and level mode interrupts are supported
  - Only IRQ14 is supported
  - Miscellaneous Features: Max Twins 0, -Audio, -ReadOnly, +PowerDown
17. 008E: Code 1B, link 06  
03 01 21 B5 1E 4D  
Tuple CISTPL\_CFTABLE\_ENTRY (1B), length 6 (06) at offset 8E
  - Configuration Table Index is 03
  - Vcc Power Description: Nom V = 3.30 V, Peak I = 45.0 mA
18. 0096: Code 14, link 00  
Tuple CISTPL\_NO\_LINK (14), length 0 (00) at offset 96
19. 0098: Code FF  
Tuple CISTPL\_END (FF) at offset 98

#### 4.4 Identify Drive Parameter Information

An example of the parameter information received from the CF Card when invoking the Identify Drive command (ECh) is listed in Table 22.

Table 22: Identify Drive Parameter Information

Word Address	Data	Total Bytes	Description
0	848AH	2	Value fixed by CFA (value=044AH for part numbers with F suffix)
1	XXXXH	2	Default number of cylinders
2	0000H	2	Reserved
3	00XXH	2	Default number of heads
4	XXXXH	2	Do not use this word. Before retirement, was number of unformatted bytes per track
5	XXXXH	2	Do not use this word. Before retirement, was number of unformatted bytes per sector
6	XXXXH	2	Default number of sectors per track
7 - 8	XXXXH	4	Number of sectors per CF Card (word 7 = MSW, word 8 = LSW)
9	0000H	2	Reserved
10 - 19	Unique per card	20	Serial Number in ASCII (20 characters): STEC proprietary
20	XXXXH	2	Do not use this word. Before retirement, was buffer type
21	XXXXH	2	Do not use this word. Before retirement, was buffer size in 512 byte increments
22	0004H	2	# of ECC bytes passed on Read/Write Long commands
23 - 26	See description	8	Firmware revision in ASCII (8 characters): Rev8.0.0 52 65 76 38 2E 30 2E 30 hex
27 - 46	See description	40	Model Number in ASCII (40 characters): STI Flash 8.0.0 <left justified> 53 54 49 20 46 6C 61 73 68 20 38 2E 30 2E 30 20 hex
47	0001H	2	Maximum of 1 sector on Read/Write Multiple command
48	0000H	2	Double Word not supported
49	0300H	2	DMA supported, LBA supported (0200H DMA not supported, LBA supported for part numbers with P)
50	0000H	2	Reserved
51	0200H	2	PIO data transfer cycle timing mode
52	0000H	2	Single word DMA data transfer cycle timing mode (not supported)
53	0003h	2	Words 54 - 58 and 64 - 70 are valid
54	XXXXH	2	Number of Current Cylinders
55	XXXXH	2	Number of Current Heads
56	XXXXH	2	Number of Current Sectors Per Track
57	XXXXH	2	LSW of the Current Capacity in Sectors
58	XXXXH	2	MSW of the Current Capacity in Sectors
59	010XH	2	Current Setting for Block Count=1 for R/W Multiple commands
60 - 61	XXXXH	4	Total number of sectors addressable in LBA Mode
62	0000H	2	Single word DMA transfer not supported
63	0407H	2	Multiword DMA modes supported (0000H Multiword DMA modes not supported for part numbers with P)
64	0003H	2	Advanced PIO modes supported (modes 3 and 4)
65	0078H	2	Minimum multiword DMA transfer cycle time per word (ns) (0000H for part numbers with P)
66	0078H	2	Recommended multiword DMA transfer cycle time per word (ns) (0000H for part numbers with P)
67	0078H	2	Minimum PIO transfer without flow control
68	0078H	2	Minimum PIO transfer with IORDY flow control
69 - 255	0000H	374	Reserved

XXXXH = These values depend on the specific CF Card.

## 5.0 Registers

This chapter lists the registers of the CF Card. Refer to CF Card standards for further details.

### 5.1 Configuration Registers

In PC Card Mode, four configuration registers, as listed in Table 23, are used.

*Note: In True IDE Mode, these registers cannot be used.*

Table 23: Configuration Registers

Configuration Register	Description
Configuration Option Register	This register is used to configure and observe the status of the CF Card, and to issue soft resets to it. Also, the Index bits of this register are used to select the PC Card mapping mode that the CF Card uses: 1) PC Card Memory, 2) PC Card Contiguous I/O, 3).PC Card Primary I/O, and 4) PC Card Secondary I/O
Configuration and Status Register	This register is used for observing the CF Card state.
Pin Replacement Register	This register is used for providing the signal state of -IREQ when the CF Card is configured in the PC Card I/O Mode.
Socket and Copy Register.	This read/write register is used to identify the CF Card from other devices. This register should be set by the host before this Configuration Option register is set.

## 5.2 Task File Registers

Table 24: CF Card Task File Registers

Task File Register	Description
Data Register	The Data Register is a 16-bit read/write register used for transferring data between the CF Card and the host. This register can be accessed in word mode and byte mode.
Error Register	The Error Register is a read-only register that is used for analyzing an error. This register is valid when the BSY bit in the Status register and Alternate Status register are set to "0" (Ready). Diagnostic Codes are returned in the Error Register after a Execute Drive Diagnostic command (code 90h). Extended Error Codes returned in the Error Register after a Request Sense command (code 03h).
Sector Count Register	This register contains the numbers of sectors of data requested to be transferred on a read or write operation between the host and the CF Card. If the value in the register is 0, a count of 256 sectors is indicated.
Sector Number Register	When the LBA bit in the Drive/Head register is 0, this register contains the starting sector number for any media access. When the LBA bit is set to 1, this register contains bits 7:0 of the LBA for any media access.
Cylinder Low Register	In CHS mode (LBA=0), this register contains the low-order bits of the starting cylinder address. In LBA mode, it contains bits 15:8 of the LBA.
Cylinder High Register	In CHS mode (LBA=0), this register contains the high-order bits of the starting cylinder address. In LBA mode, it contains bits 23:16 of the LBA.
Drive/Head Register	This register selects the CF Card address translation (CHS or LBA) and provides head address (CHS) or high-order address bits 27:24 for LBA.
Status Register	This read-only register indicates status of a command execution. When the BSY bit is "0", the other bits are valid; when the BSY bit is "1", the other bits are not valid. When the register is read, the interrupt pin, is cleared.
Alternate Status Register	This register is the same as the Status register, except that is not negated when the register is read.
Device Control Register	This write-only register is used for controlling the interrupt request and issuing an ATA soft reset to the CF Card.
Drive Address Register	This read-only register is used for confirming the CF Card's status. This register is provided for compatibility with the AT disk drive interface and it is not recommended that this register be mapped into the host's I/O space because of potential conflicts on bit 7.
Command Register	This write-only register is used for writing the command that executes the CF Card's operation. The command code is written in the command register after its parameters are written in the Task File during the CF Card ready state.



## 6.0 Supported ATA Commands

The ATA commands used by the CF Card are listed in Table 25. Refer to CF Card standards for details.

Table 25: CF Card Supported ATA Commands

Command Set	Code	Description
Check Power Mode	E5h or 98h	This command checks the power mode.
Execute Drive Diagnostic	90h	This command performs the internal diagnostic tests implemented by the CF Card. The Diagnostic Code is returned in the Error Register.
Erase Sector(s)	C0h	Command is used to pre-erase/condition data sectors in advance.
Format Track	50h	Command writes the desired head/cylinder of the selected drive with a vendor unique data pattern (typically 00h or FFh). CF Card accepts a sector buffer of data from the host to follow the command with the same protocol as the Write Sector Command although the information in the buffer is not used.
Identify Drive	ECh	This command lets the host receive parameter information from the CF Card in the same protocol as Read Sector(s) command.
Idle	E3h or 97h	Command causes the CF Card to set BSY, enter the Idle mode, clear BSY, and generate an interrupt. If the sector count is non-zero, automatic power down mode is enabled. If the sector count is zero, the automatic power down mode is disabled.
Idle Immediate	E1h or 95h	This command causes the CF Card to set BSY, enter the Idle mode, clear BSY, and generate an interrupt.
Initialize Drive Parameters	91h	This command enables the host to set the number of sectors per track and the number of heads per cylinder.
NOP	00h	No Operation.
Read Buffer	E4h	This command enables the host to read the current contents of the CF Card's sector buffer.
Read DMA (Not used for part numbers with P)	C8h	This command is the sector read command used for Multiword DMA transfer.
Read Multiple	C4h	This command performs similarly to the Read Sectors command. Interrupts are not generated on each sector, but on the transfer of a block which contains the number of sectors defined by a Set Multiple command.
Read Long Sector	22h or 23h	Command performs similarly to the Read Sector(s) command except that it returns 516 bytes of data instead of 512 bytes.
Read Sector(s)	20h (w/ retry) 21h (w/o retry)	Command reads from 1 to 256 sectors as specified in the Sector Count register. Sector count of 0 requests 256 sectors. Transfer begins at the sector specified in the Sector Number register.
Read Verify Sector(s)	40h (w/ retry) 41h (w/o retry)	This command verifies one or more sectors on the CF Card by transferring data from the flash media to the data buffer in the CF Card and verifying that the ECC is correct. This command is identical to the Read Sectors command, except that DRQ is never set and no data is transferred to the host.
Recalibrate	1Xh	The CF Card performs only the interface timing and register operations. When this command is issued, the CF Card sets BSY and waits for an appropriate length of time, after which it clears BSY and issues an interrupt. When this command ends normally, the CF Card is initialized.
Request Sense (Extended Error)	03h	This command requests an extended error code after a command ends with an error. The extended error code is returned in the Error Register

Command Set	Code	Description
Seek	7Xh	This command is effectively a NOP command to the CF Card although it does perform a range check.
Set Features	EFh	Command is used by host to establish or select certain features.
Set Multiple Mode	C6h	This command enables the CF Card to perform multiple read and write operations and establishes the block count for these commands.
Set Sleep Mode	E6h or 99h	This is the only command that allows the host to set the CF Card into Sleep mode. When the CF Card is set to sleep mode, the CF Card clears the BSY line and issues an interrupt. The CF Card enters sleep mode and the only method to make the CF Card active again (back to normal operation) is by performing a hardware reset or a software reset.
Stand By	E2h or 96h	This command sets the CF Card in Standby mode. If the Sector Count Register is a value other than 0H, an Auto Power Down is enabled and when the CF Card returns to the idle mode, the timer starts a countdown. The time is set in the Sector Count Register.
Stand By Immediate	E0h or 94h	This command causes the CF Card to set BSY, enter the Standby mode, clear BSY and return the interrupt immediately.
Translate Sector	87h	This command allows the host a method of determining the exact number of times a user sector has been erased and programmed. This command is not supported.
Wear Level	F5h	This command is effectively a NOP command and only implemented for backward compatibility. The Sector Count Register will always be returned with an 00h indicating Wear Level is not needed.
Write Buffer	E8h	This command enables the host to overwrite the contents of the CF Card's sector buffer with any data pattern desired.
Write DMA (Not used for part numbers with P)	CAh	This command is the sector write command used for Multiword DMA transfer.
Write Long Sector	32h or 33h	This command is provided for compatibility purposes and is similar to the Write Sector(s) command except that it writes 516 bytes instead of 512 bytes.
Write Multiple	C5h	This command is similar to the Write Sectors command. Interrupts are not presented on each sector, but on the transfer of a block which contains the number of sectors defined by Set Multiple command.
Write Multiple w/o Erase	CDh	This command is similar to the Write Multiple command, except that an implied erase before the write operation is not performed. <b>Note:</b> Before using this command, it is required to erase the respective sectors using the Erase Sectors command
Write Sector(s)	30h (w/ retry) 31h (w/o retry)	This command writes from 1 to 256 sectors as specified in the Sector Count register. A sector count of zero requests 256 sectors. The transfer begins at the sector specified in the Sector Number register.
Write Sector(s) w/o Erase	38h	This command is similar to the Write Sector(s) command, except that an implied erase before the write operation is not performed. <b>Note:</b> Before using this command, it is required to erase the respective sectors using the Erase Sectors command.
Write Verify	3Ch	This command is similar to the Write Sector(s) command except each sector is verified immediately after being written.

## 7.0 Appendix: CompactFlash Adapter

In addition to the CF Card form factors, passive CompactFlash Adapters allow the cards to be used in a PC Card Type II slot. This appendix provides information on CompactFlash Adapters available from STEC.

### 7.1 CF Adapter Ordering Information

Refer to Table 26 for CF Adapter part numbers.

Table 26: CF Adapter Ordering Information

Part Number	CF Form Factor	PC Card Form Factor
SLCFAD(I)U	Type I	Type II
SLCFAD2(I)U	Type I or Type II	Type II

**Legend:**

- **SLCFAD, SLCFAD2 = STEC** standard CompactFlash Adapter part number prefix.
- **Part numbers without (I)** = Commercial temperature range (0°C to 70°C).
- **I** = Industrial temperature range (-40°C to +85 °C)
- **U** = RoHS-6 compliant lead-free.

### 7.2 CF Adapter Specifications

Table 27: CF Adapter Specifications

Parameter	Value
Mating/unmating life	10,000 cycles
Operating voltage	240 VAC max
Current rating	1A max
Contact resistance	3 ohms max
Insulation resistance	200M ohms min (300V DC)
Commercial Operating Temperature	0°C to 70°C
Industrial Operating Temperature	-40°C to +85 °C
Lead content	RoHS-6 compliant, lead-free

7.3 CF Adapter Package Dimensions and Pin Locations

Table 28 and Figure 14 show the mechanical dimensions of the CF Adapters, Type I and Type II.

Table 28: Mechanical dimensions CF Adapter (Type I and Type II)

Parameter	Value
Length	85.50 ± 0.20 mm (3.366 ± 0.008 in)
Width	54.40 ± 0.10 mm (2.126 ± 0.004 in)
Height (including label area)	5.00 mm (0.197 in) max

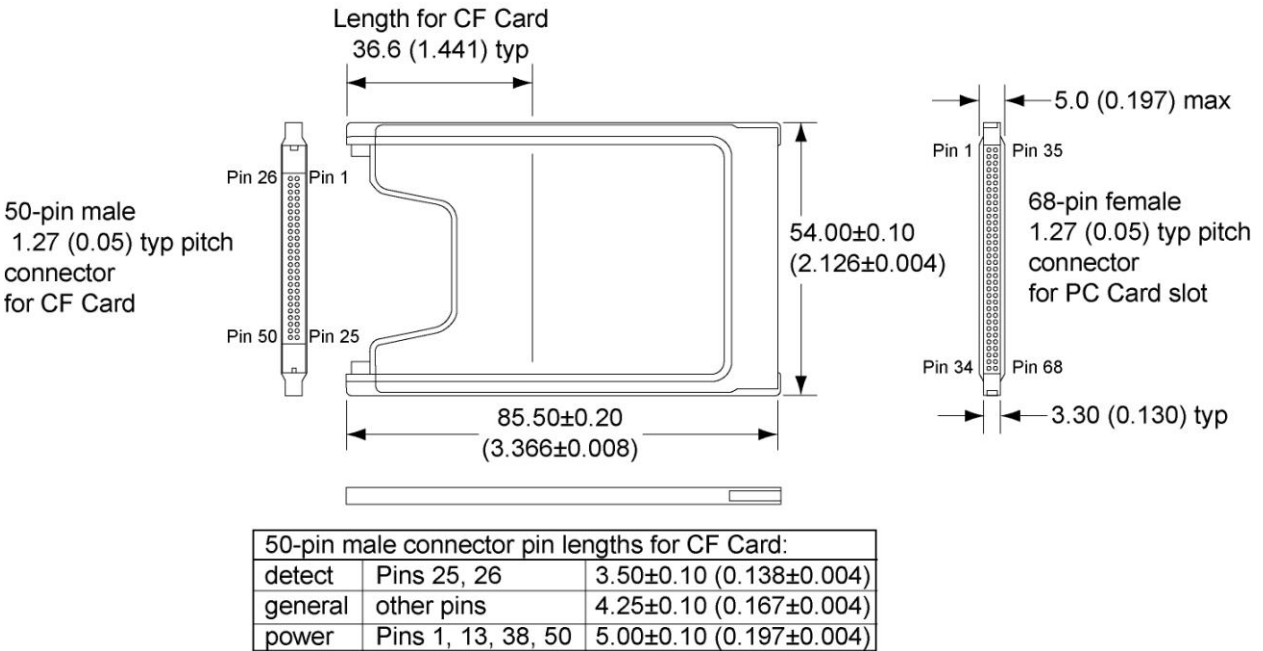


Figure 14: Mechanical dimensions CF Adapters (Type I and Type II)

## 7.4 CF Adapter Pin Assignment

Table 29: CF Adapter Pin Assignment

Pin Number	PC Card	CF Card	Pin Number	PC Card	CF Card
1	GND	GND	35	GND	-IOWR
2	D03	D03	36	-CD1	-WE
3	D04	D04	37	D11	-RDY/-BSY, -IREQ, INTRQ
4	D05	D05	38	D12	VCC
5	D06	D06	39	D13	-CSEL
6	D07	D07	40	D14	-VS2
7	-CE1, -CS0	-CE1, -CS0	41	D15	RESET, -RESET
8	A10	A10	42	-CE2, -CS1	-WAIT, IORDY
9	-OE, -ATASEL	-OE, -ATASEL	43	-VS1	-INPACK, DMARQ
10		A09	44	-IORD	-REG, -DMACK
11	A09	A08	45	-IOWR	BVD2, -SPKR, -DASP
12	A08	A07	46		BVD1, -STSCHG, -PDIAG
13		VCC	47		D08
14		A06	48		D09
15	-WE	A05	49		D10
16	-RDY/-BSY, -IREQ, INTRQ	A04	50		GND
17	VCC	A03	51	VCC	
18		A02	52		
19		A01	53		
20		A00	54		
21		D00	55		
22	A07	D01	56		
23	A06	D02	57	-VS2	
24	A05	WP, -IOIS16	58	RESET, -RESET	
25	A04	-CD2	59	-WAIT, IORDY	
26	A03	-CD1	60	-INPACK, DMARQ	
27	A02	D11	61	-REG, -DMACK	
28	A01	D12	62	BVD2, -SPKR -DASP	
29	A00	D13	63	BVD1, -STSCHG, -PDIAG	
30	D00	D14	64	D08	
31	D01	D15	65	D09	
32	D02	-CE2, -CS1	66	D10	
33	WP, -IOIS16	-VS1	67	-CD2	
34	GND	-IORD	68	GND	

Legend: "-" = Low active

## 8.0 Revision History

<b>Revision</b>	<b>Date</b>	<b>Description</b>
-101	11/17/06	Product release.
-102	12/3/06	S option added to Ordering Information Legend and CHS parameters table.
-103	12/11/06.	P option added to Ordering Information Legend. Where MWDMA is documented, it is noted that N/A to part numbers with P.
-104	12/14/06	ID file entries for Serial Number, Firmware Revision, and Model Number corrected in table.
-105	1/16/07	Logo updated. Disclaimer updated. Contact Information added.
-106	1/23/07	In between capacities removed from Ordering Information and CHS parameters. Serial number revision (paper correction only).
-107	2/28/07	CSEL signal description corrected. 16GB CHS parameters added. DC Characteristics corrected
-108	4/10/07	Shock updated from 1K to 1.5K. Vibration updated from 15 to 20.
-109	5/9/07	Power up/RESET to RDY timing added.
-110	5/21/07	Labeling section added.
-111	6/11/07	Connector location added to Labeling section. Label added to dimension illustrations.
-112	8/06/07	Warranty bullet removed from features column on page 1
-113	9/17/07	General Description text updated.
-114	11/2/07	Pasting error corrected in CIS (paper error only).
-115	11/7/07	Layout updated for consistency and easier editing. Disclaimer notice reformatted with headings.
-116	11/21/07	S option cylinder count corrected.
-117	3/7/08	Contact information on last page updated.
-118	4/2/08	STEC China address on last page updated.

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